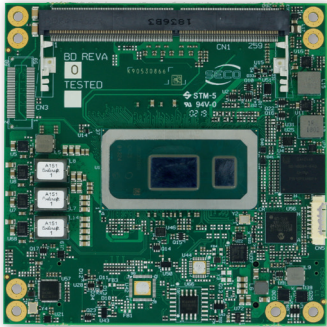




## COMe-C55-CT6

COM Express® 3.0 Compact Type 6 module with the 8th Gen Intel® Core™ and Celeron™ 4000 series processors (formerly Whiskey Lake)

Low power multi-core Intel® architecture for mobile applications



### HIGHLIGHTS

<b>CPU</b> 8th Gen Intel® Core™ and Celeron™ 4000 series processors (formerly Whiskey Lake) with 15W TDP	<b>CONNECTIVITY</b> 4 x USB 3.1; 8 x USB 2.0, up to 8 x PCI-e x 1
<b>GRAPHICS</b> Intel® UHD Graphics 620 / 610	<b>MEMORY</b> Two DDR4 SO-DIMM Slots supporting DDR4-2400 Memory, up to 64GB



### MAIN FIELDS OF APPLICATION



### FEATURES

<b>Processor</b> Intel® Core™ <b>i7-8665UE</b> , Quad Core @ 1.7GHz (Turbo Boost 4.4GHz) with HT, 8MB Cache, 15W TDP (12.5W..25W cTDP) Intel® Core™ <b>i5-8365UE</b> , Quad Core @ 1.6GHz (Turbo Boost 4.1GHz) with HT, 6MB Cache, 15W TDP (12.5W..25W cTDP) Intel® Core™ <b>i3-8145UE</b> , Dual Core @ 2.2GHz (Turbo Boost 3.9GHz) with HT, 4MB Cache, 15W TDP (12.5W..25W cTDP) Intel® Celeron® <b>4305UE</b> , Dual Core @ 2.0GHz, 2MB Cache, 15W TDP	<b>USB</b> 4 x USB 3.1 Host ports 8 x USB 2.0 Host ports
<b>Max Cores</b> 4	<b>PCI-e</b> Up to 8 x PCI-e x 1 lanes Optional PCI-express Graphics (PEG) x2 or x4 Possible configurations (factory alternative): • 8 ports PCI-e x1 • 6 ports PCI-e x 1 + PEG x2 • 5 ports PCI-e x 1 + PEG x4 • 4 ports PCI-e x 1 + PEG x4 + 3rd SATA
<b>Max Thread</b> 8	<b>Audio</b> HD Audio Interface
<b>Memory</b> Two DDR4 SO-DIMM Slots supporting DDR4-2400 Memory, up to 64GB	<b>Serial Ports</b> 2x UARTs
<b>Graphics</b> Intel® UHD Graphics 620 (Core™ processors), 610 (Celeron™ processor) Up to 3 independent display supported DirectX 12, OpenGL 4.5, and OpenCL 2.1 support HW accelerated video decode MPEG2, VC1/WMV9, AVC/H.264, VP8, JPEG/MJPEG, HEVC/H.265 (8 and 10 bits), VP9 HW accelerated video encode MPEG2, AVC/H.264, VP8, JPEG, HEVC/H.265, VP9	<b>Other Interfaces</b> SPI, I2C, SM Bus, LPC bus, FAN management Optional TPM 2.0 module on-board LID#/SLEEP#/PWRBTN#, Watchdog 4x GPI, 4 x GPO
<b>Video Interfaces</b> Up to 2 x Digital Display Interfaces (DDIs), supporting DP 1.2, eDP 1.4, HDMI 1.4 and DVI eDP or Single/Dual-Channel 18-/24- bit LVDS interface Optional VGA interface (excludes DDI port #2)	<b>Power Supply</b> +12V <sub>DC</sub> ± 10% and +5V <sub>SB</sub> (optional)
<b>Video Resolution</b> eDP, DP: up to 4096 x 2304 @60Hz HDMI: up to 4096 x 2160 @30Hz LVDS: up to 1920 x 1200 @ 60Hz VGA: up to 2048 x 1536 @ 50Hz (reduced blanking)	<b>Operating System</b> Microsoft Windows 10 Enterprise / IoT Linux Yocto
<b>Mass Storage</b> Up to 3 x S-ATA Gen3 Channels Optional eMMC 5.1 drive on-board microSD Card slot on-board	<b>Operating Temperature*</b> 0°C ÷ +60°C (Commercial version)
<b>Networking</b> Gigabit Ethernet interface Intel® I219-LM GbE Controller	<b>Dimensions</b> 95 x 95 mm (Com Express™ Compact Form factor, Type 6 pinout)

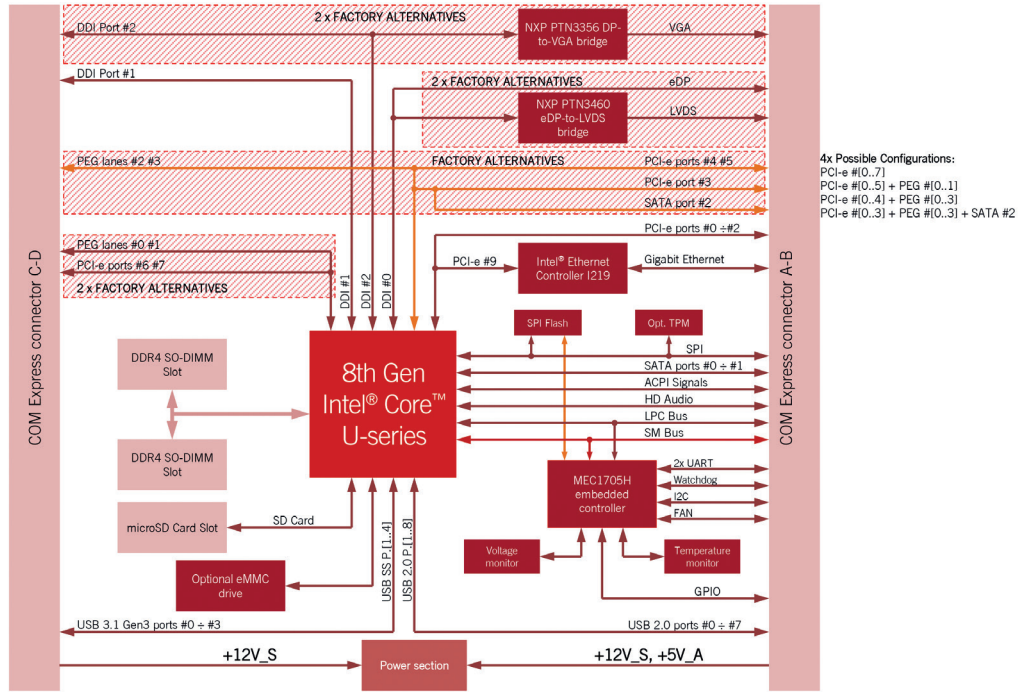
\*Measured at any point of SECO standard heatspreader for this product, during any and all times (including start-up). Actual temperature will widely depend on application, enclosure and/or environment. Upon customer to consider application-specific cooling solutions for the final system to keep the heatspreader temperature in the range indicated.



# COMe-C55-CT6

## COM Express® 3.0 Compact Type 6 module with the 8th Gen Intel® Core™ and Celeron™ U-series processors (formerly Whiskey Lake)

### BLOCK DIAGRAM



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